	L #	Hits	Search Text	DBs	Time Stamp
1	L1	0	scarificial adj(base core substrate workpiece piece object)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2003/05/05 10:27
2	L2	391	sacrificial adj(base core substrate workpiece piece object)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2003/05/05 10:29
3	L3	10	2 and isostatic$5 adj press$4	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2003/05/05 10:30

HIP, hot pressy

L4 (29) 2 and ((hot heat$4) adj press$4 or HIP) not 3

L5 (3) 2 and (metallurgic$5 adj Bond$4) not (3 or 4)

SN09/887,757

	Document ID	Issue Date	Title	Current OR	Inventor
1	US 20030027373 A1	20030206	Methods for providing void-free layers for semiconductor assemblies	438/106	DiStefano, Thomas H. et al.
2	US 20020136840 A1	20020926	Corrosion resistant component and method for fabricating same	427/446	Hebeisen, John C. et al.
3	US 20020094671 A1	20020718	Methods for providing void-free layers for semiconductor assemblies	438/612	Distefano, Thomas H. et al.
4	US 6458681 B1	20021001	Method for providing void free layer for semiconductor assemblies	438/612	DiStefano, Thomas H. et al.
5	US 6107123 A	20000822	Methods for providing void-free layers for semiconductor assemblies	438/125	Distefano, Thomas H. et al.

	Document ID	Issue Date	Title	Current OR	Inventor
6	US 5834339 A	19981110	Methods for providing void-free layers for semiconductor assemblies	438/125	Distefano, Thomas H. et al.
7	US 5822853 A	19981020	Method for making cylindrical structures with cooling channels	29/890.01	Ritter, Ann Melinda et al.
8	US 5206083 A	19930427	Diamond and diamond-like films and coatings prepared by deposition on substrate that contain a dispersion of diamond particles	428/323	Raj, Rishi et al.
9	US 5183602 A	19930202	Infra red diamond composites	252/587	Raj, Rishi et al.

	Document ID	Issue Date	Title	Current OR	Inventor
10	US 4370789 A	19830201	Fabrication of gas turbine water-cooled composite nozzle and bucket hardware employing plasma spray process	29/889.722	Schilke, Peter W. et al.

L4

#10 6,349,700 Sweatt et al

See Figs. 8 + (D27) In Fig 8 ... coresuspension 53 formed in core sacrif. sub...

(D28) ..

Jumbo + poor

#16 6,336,269 Eldridge et al

Figs. 11, desc. (D459-468) - sacrif. sub 1104 + multilayer, but no encapsulation

no coat poor

#27 4,344,134 Hilton

Figs. 1, 2, 3, 5-17 — sacrif. core portion

(D1) Turning now to Fig. 1 ... low density sacrif. portion 16 — temp. sustained

(D3) Subsequent to achieving assembly of thermocouple w/), "bagged" curves w/ heat + pressure → debagging + 16 removal by pull away attach

L5

	Document ID	Issue Date	Title	Current OR	Inventor
1	US 6229100 B1	20010508	Low profile socket for microelectronic components and method for making the same	174/261	Fjelstad, Joseph
2	US 6060341 A	20000509	Method of making an electronic package	438/123	Alcoe, David James et al.
3	US 5983492 A	19991116	Low profile socket for microelectronic components and method for making the same	29/843	Fjelstad, Joseph

(B12) mech phrase rather than unbalanced bracket